

11-21-2005

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Kazuaki Yazawa, Toshiyuki Hiroi

Execution Date(s) 11/04/2005

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: Sony Computer Entertainment Inc.

Internal Address:

Street Address: 2-6-21, Minami-Aoyama

City: Minato-ku

State: Tokyo

Country: Japan Zip: 107-0062

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

☒ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Mark L. Berrier

Internal Address: Building 2, Suite 300

Street Address: 1250 Capital of Texas Hwy. S.

City: Austin

State: Texas Zip: 78746

Phone Number: 512-329-2655

Fax Number: 512-330-1710

Email Address: mberrier@texasIP.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☒ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers 9357
Expiration Date 10/07

b. Deposit Account Number

Authorized User Name

9. Signature:

Signature

Mark L. Berrier

Name of Person Signing

11/10/2005
Date

Total number of pages including cover sheet, attachments, and documents:

3

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

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PATENT
REEL: 017236 FRAME: 0350

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in: **SYSTEMS AND METHODS FOR THERMAL MANAGEMENT**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Computer Entertainment Inc., a Japanese corporation with offices at 2-6-21, Minami-Aoyama, Minato-ku, Tokyo, 107-0062 Japan, (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said applications, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patent, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of my whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said applications for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment executed on the dates indicated below.

Kazuaki Yazawa
Name of First or Sole Inventor

526-3, Matsudoshinden, Matsudo, Chiba 270-2241 Japan
Residence of First or Sole Inventor

矢澤 和明
Signature of First or Sole Inventor

11/04/2005
Date of this Assignment

Toshiyuki Hiroi

Name of Second Joint Inventor

Saitama, Japan

Residence of Second Joint Inventor



Signature of Second Joint Inventor

08 Nov 2005

Date of this Assignment

Name of Third Joint Inventor

Residence of Third Joint Inventor

Signature of Third Joint Inventor

Date of this Assignment

Name of Fourth Joint Inventor

Residence of Fourth Joint Inventor

Signature of Fourth Joint Inventor

Date of this Assignment